

#### FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

#### 14 Oct 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification # 16165

TITLE: Final Notification for Gold wire changing to Copper wire on SOT-23 BRT parts

PROPOSED FIRST SHIP DATE: 14 Jan 2009

AFFECTED CHANGE CATEGORY: ON Semiconductor assembly - wire bond

**AFFECTED PRODUCT DIVISION: Discrete Products** 

FOR SAMPLES: Contact your local ON Semiconductor Sales Office

## FOR ANY QUESTIONS CONCERNING RELIABILITY DATA:

Contact your local ON Semiconductor Sales Office or Laura Rivers <a href="mailto:laura.rivers@onsemi.com">laura.rivers@onsemi.com</a>>

#### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Calvin Lim<a href="mailto:calvin.lim@onsemi.com">com</a>>

### **NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

# **DESCRIPTION AND PURPOSE:**

This is the FPCN to IPCN 16009 available at <a href="www.onsemi.com">www.onsemi.com</a>. On Semiconductor is notifying customers of its plan to convert to Copper wire on Bias Resistor Transistor (BRT) products in the SOT-23 package.

The mold compound, die attach, and lead frame materials used in the SOT-23 package will remain the same. Two qualification vehicles, a transistor and a diode, have been selected for each of the device functions and full electrical characterization of the BRTs over temperature has be performed on each BRT vehicle to ensure device functionality and electrical specifications are met.

Devices listed in this final PCN will be converted to Copper wire starting WW0109. After January 01, 2009, customer may receive devices with either Gold or Copper as conversion is implemented in our assembly facility. Conversion of specific devices will take place at the beginning of the specified month and devices containing Copper wire can be identified by the date code (1 or greater).

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## **QUALIFICATION PLAN:**

Reliability testing was performed on qualification vehicles chosen based on die size, voltage rating, and run rates.

#### **RELIABILITY RESULTS:**

#### BCX19LT1G:

| MSL Preconditioning | JEDEC MSL 1 @ 260C          |              | 0/1992 |
|---------------------|-----------------------------|--------------|--------|
| HTSL                | Ta = 150C, 1008 hrs         |              | 0/504  |
| Autoclave + PC      | Ta=121C, RH=100%, psig~14   | .7 96 hrs    | 0/504  |
| Temp Cycle + PC     | Ta= -65/150C 1000 cycles    |              | 0/504  |
| H3TRB + PC          | Ta= 85C, RH=85%, 80% bias   | 1008 hrs     | 0/504  |
| IOL +PC             | Ta=25C, delta Tj = 100C max |              |        |
|                     | Ton=Toff= 2min              | 15000 cycles | 0/504  |

#### BAS21LT1G

| MSL Preconditioning | JEDEC MSL 1 @ 260C           |            | 0/960 |
|---------------------|------------------------------|------------|-------|
| HTRB                | Ta=150C, 1008 hrs , 80% bias | 1008 hrs   | 0/320 |
| IOL +PC             | Ta=25C, delta Tj = 100C max  |            |       |
|                     | Ton=Toff= 2min 150           | 000 cycles | 0/320 |
| Temp Cycle + PC     | Ta= -65/150C 1000 cycles     |            | 0/319 |
| Autoclave + PC      | Ta=121C, RH=100%, psig~14.7  | 96 hrs     | 0/320 |
| H3TRB + PC          | Ta= 85C, RH=85%, 80% bias    | 1008 hrs   | 0/320 |
| HTSL                | Ta = 150C, 1008 hrs          |            | 0/320 |

# **ELECTRICAL CHARACTERIZATION PLAN:**

Datasheet specifications and product electrical performance will remain unchanged

Characterization of each BRT device will be performed at three temperatures on 30 units from 3 lots

## **ELECTRICAL CHARACTERIZATION RESULTS:**

Available upon request

#### CHANGED PART IDENTIFICATION:

Conversion of specific devices will take place at the beginning of the specified month, January 1<sup>st</sup>, 2009, and devices containing Copper wire can be identified by the date code (1 or greater).

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# **ON Semiconductor**



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## AFFECTED DEVICE LIST:

MMUN2111LT1

MMUN2111LT1G

MMUN2111LT3G

MMUN2112LT1G

MMUN2113LT1G

MMUN2113LT3G

MMUN2114LT1G

MMUN2115LT1

MMUN2115LT1G

MMUN2116LT1G

MMUN2132LT1G

MMUN2133LT1G

MMUN2211LT1

MMUN2211LT1G

MMUN2211LT3G

MMUN2212LT1G

MMUN2213LT1G

MMUN2214LT1G

MMUN2215LT1G MMUN2216LT1G

MMUN2231LT1G

MMUN2232LT1G

MMUN2233LT1G

MMUN2234LT1

MMUN2234LT1G

MMUN2238LT1G

NSVMMUN2232LT1G

SMMUN1003LT1

SMMUN1003LT1G

SMMUN1004LT1

SMMUN1004LT1G

SMMUN2111LT1

SMMUN2111LT1G

SMMUN2111LT3

SMMUN2111LT3G

SMMUN2113LT1

SMMUN2113LT1G

SMMUN2114LT1G

SMMUN2116LT1

SMMUN2116LT1G

SMMUN2211LT1 SMMUN2211LT1G

SMMUN2211LT3

SMMUN2211LT3G

SMMUN2213LT1G

ON AN ALL DISCASS TO

SMMUN2213LT3

SMMUN2213LT3G SMMUN2214LT1

SMMUN2214LT1G

SMMUN2216LT1

SMMUN2216LT1G

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